

ABSTRACT OF THE DISCLOSURE

A semiconductor device formed by cutting a first substrate and a second substrate bonded together by a spacer, wherein: the spacer is disposed at an end of  
5 the first substrate after cutting; the second substrate is a semiconductor wafer formed with a light reception element or elements; and the first substrate has an optical element or an optical element set for converging light on the light reception element or  
10 elements. A method of manufacturing such a semiconductor device. A semiconductor device manufacture method includes: a step of detecting a warp of a semiconductor substrate; a step of holding the semiconductor substrate on a base under a condition  
15 that the warp is removed; a step of bonding an opposing substrate to the semiconductor substrate; and a step of cutting the opposing substrate, wherein the opposing substrate bonded to the semiconductor substrate is set with a size corresponding to the warp of the  
20 semiconductor substrate or with a gap to an adjacent opposing substrate.